The 18th International Symposium on Laser Precision Microfabrication
Toyama International Conference Center, Toyama, Japan
June 5 to June 8, 2017
http://www.jlps.gr.jp/lpm/lpm2017/

LPM 2017

AIM AND SCOPE:

Miniaturization and high precision are rapidly becoming requirements in many industrial processes and products. As a result, there is greater interest in the use of laser micro fabrication approaches to achieve these goals. The International Symposium on Laser Precision Microfabrication (LPM) is alternatively held in Japan and in other host countries. To date, LPM has been successfully hosted in Omiya, Singapore, Osaka, Munich, Nara, Williamsburg, Kyoto, Vienna, Quebec, Kobe, Stuttgart, Takamatsu, Washington D.C., Niigata, Vilnius, Kokura and Xi'an. The aim of this symposium is to provide a forum for discussion of fundamental aspects of laser-matter interaction, the state-of-the-art of laser materials processing, and topics for the next generation with fundamental scientists, end users and laser manufactures. We expect that LPM2017 would play an important role not only for understanding fundamental knowledge of laser precision microfabrication but also forecasting future technologies to be developed and the future laser market.

CHAIR, CO-CHAIRS, STEERING COMMITTEE CHAIR:

General Chair: Dr. Koji Sugioka, RIKEN, Japan
Co-Chairs: Dr. Hiroyuki Niino, AIST, Japan, Prof. Yongfeng Lu, University of Nebrasska-Lincoln, USA
Dr. Michael Schmidt, Friedrich-Alexander-Universität Erlangen-Nürnberg, Germany
Steering Committee Chair: Prof. Toshiya Shibayanagi, University of Toyama, Japan

ORGANIZED BY:

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TOPICS:

1. Fundamental aspects (dynamics, modeling, simulation, etc.)
2. Photochemistry
3. Process monitoring and control
4. Nanotechnology
5. Laser-based direct-write techniques
6. Ultra-short pulse laser processing
7. VUV laser and X-ray processing
8. Advanced laser sources
9. Advanced laser processing (Fiber laser, disc laser, FEL, etc.)
10. Beam shaping
11. Surface treatment
    (Texturing, cleaning, annealing, modification, etc.)
12. Nano ripple formation
13. Micro-patterning, Micro-machining and micro-structuring
14. 3-D micro- and nano-fabrication
15. Drilling and cutting
16. Welding and bonding
17. Micro-forming
18. Wafer dicing
19. Marking and trimming
20. Packaging and mounting process
21. Lithography (including EUV source and application)
22. Manufacture of micro devices and systems
23. Film deposition and synthesis of advanced materials (PLD, CVD, etc.)
24. Nano- and micro-particles
25. Optics and systems for laser microprocessing
26. Laser devices
27. Free electron laser material processing
28. High-power, single-mode fiber lasers
29. Glass/Ceramic processing
30. Medical and biological applications
31. Industrial applications
32. Others
33. Special Session (SS1): TBA
34. Special Session (SS2): TBA
35. Special Session (SS3): TBA

VENUE: **Toyama International Conference Center**

1-2 Ote-machi, Toyama, Toyama Prefecture 930-0084, Japan
Access: http://www.ticc.co.jp/english/access/

Toyama prefecture is located at the centre of Japan and serves as a gateway of the Sea of Japan. Surrounded three sides by steep mountains and faced to the deep sea, Toyama is blessed with rich nature where people can enjoy sublime scenery and tasty foods at the same time. And the Conference Center is located in the comfortable place to enjoy the sight of Toyama castle.